

Intel **Developer** Forum Fall 2002

Advancing the Digital Universe

Welcome to the Intel Developer Forum Conference Fall 2002

Frank Spindler
Vice President
Corporate Technology Group



Compaq iPAQ* Handheld

- Win a Compaq iPAQ* Handheld Computer
- Drawing at 8:00 a.m. Tuesday and Thursday
- Prize to be awarded at that time
- Get your raffle ticket at door of keynote room
- Tickets valid for same day drawing only



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Fall IDF 2002 is Wireless

Fall IDF is Wireless!

- 802.11a and 802.11b wireless LAN coverage in concourse & session rooms
- Available for laptops and Pocket PC* devices
- Free internet access!
- Wireless cards and Compaq* iPAQ PDAs for sale at the wireless connectivity solution center (concourse level)



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Be connected "anytime, anywhere"

Intel **Developer** Forum.

Fall 2002

Save the Date - Spring IDF 2003

February 18-21, 2003

San Jose, CA



*Other names and brands may be claimed as the property of others



Fill Out a Conference Survey!

- Win a Free T- shirt
- We want your opinion.
Help us improve IDF
- Fill out a survey at the Registration Booth

Intel Developer Update (IDU)

- **FREE** online monthly developer magazine
- **Technology Articles**
- **www.intel.com/update**

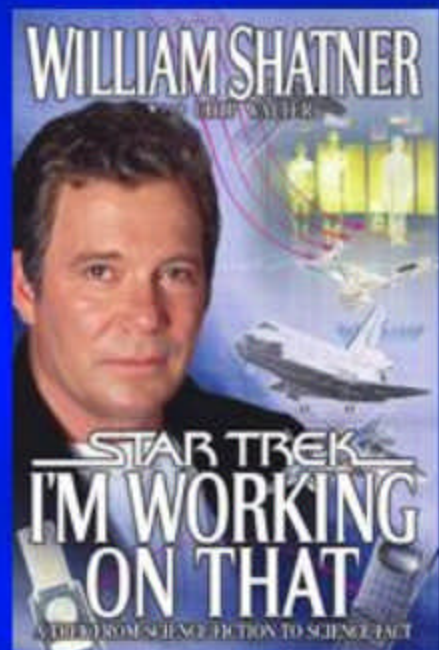


*Other names and brands may be claimed as the property of others



See William Shatner at IDF!

- Q&A session (not a book signing) with William Shatner and Chip Walter
- Authors of *Star Trek: I'm Working on That: A Trek from Science Fiction to Science Fact*
- Buy the book at the IDF Bookstore



**Thursday 8:00 a.m. at Keynote and
Thursday 12:00 – 1:00 p.m.
Room B, San Jose Convention Center**

Intel **Developer** Forum.

Fall 2002

Building the Digital Future

Pat Gelsinger

Chief Technology Officer

Vice President

Corporate Technology Group

Sunlin Chou

General Manager

Senior Vice President

Technology & Manufacturing Group

September 12, 2002





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Yesterday's Dreams



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Discovering Pathways



Alan Kay

“The best way to predict the future is to invent it.”

“Nanotechnology offers... possibilities for health, wealth, and capabilities beyond most past imaginings ”



Neil Gershenfeld

“... our goal is to embed intelligence into everyday objects...”



Eric Drexler



Video

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The Digital Future



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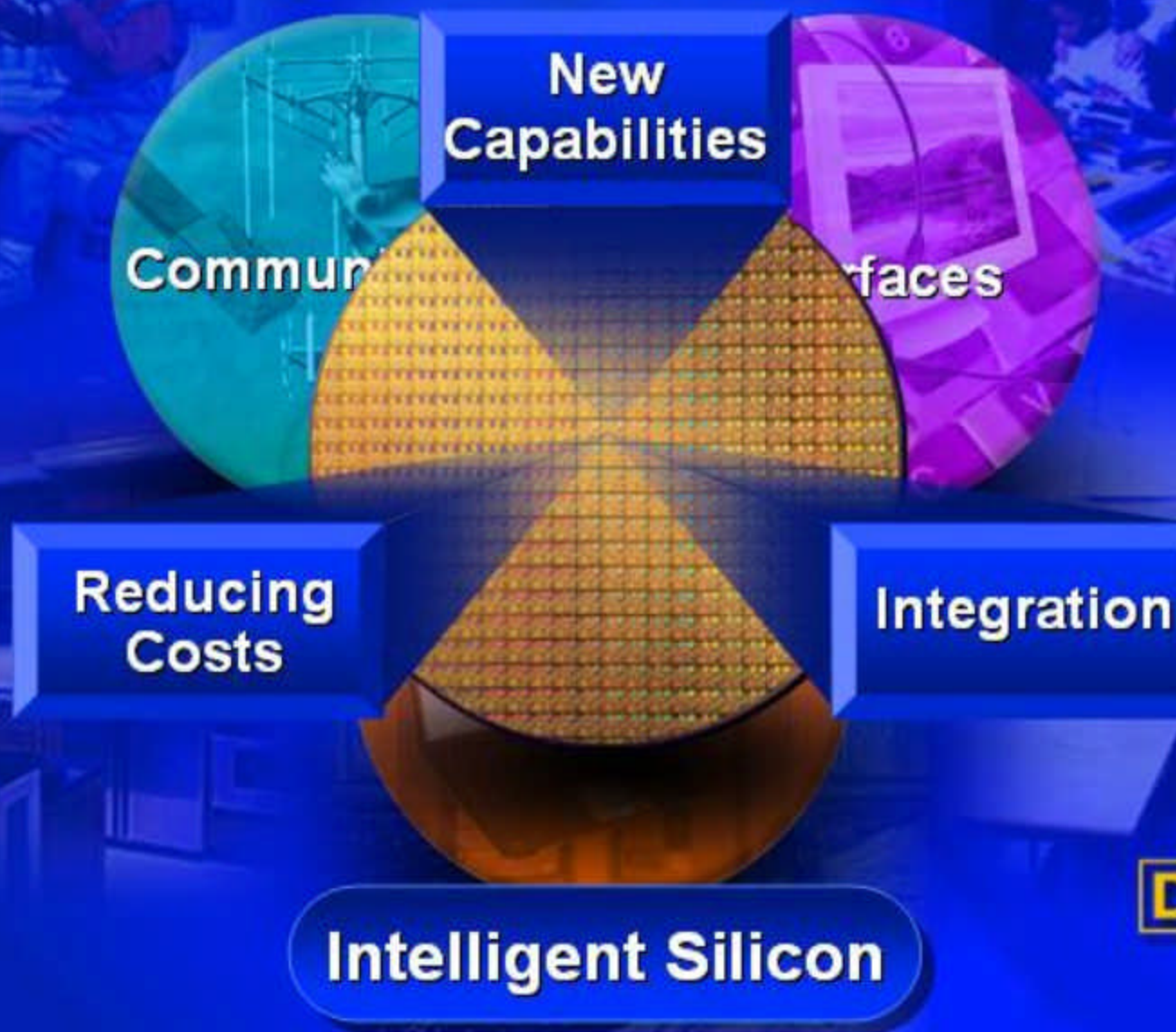
Bridge to the Digital Future

Communications

Interfaces

Computation

Silicon: The Underlying Trajectory



Moore's Law: Industry Guidepost

EXTENDING

Discrete



Moore's Law: Industry Guidepost

EXTENDING

Discrete SSI



Moore's Law: Industry Guidepost

EXTENDING

Discrete

SSI

LSI



Moore's Law: Industry Guidepost

EXTENDING

Discrete

SSI

LSI

VLSI



Moore's Law: Industry Guidepost



“Radio Free Intel”



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Fall 2002

“Radio Free Intel”: Research Areas

MEMS

**Intelligent
Roaming**

**Smart Antenna
Systems**

**Dynamically
Reconfigurable**

**Silicon
Radio**

Smart Multiple-Antenna Systems

Complex
Scheduling/Encoding

Signal Processing
Antenna Control

Benefits

Spatial
Frequency
Time



Phase
Amplitude



Capacity
Throughput
Coverage
Reliability



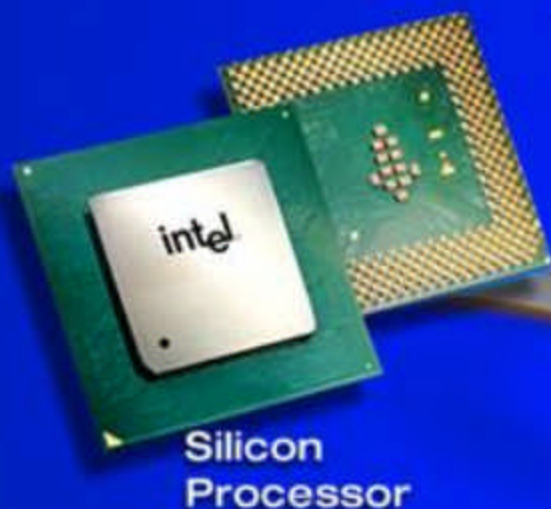
Silicon Photonics



TODAY

Silicon Electronics

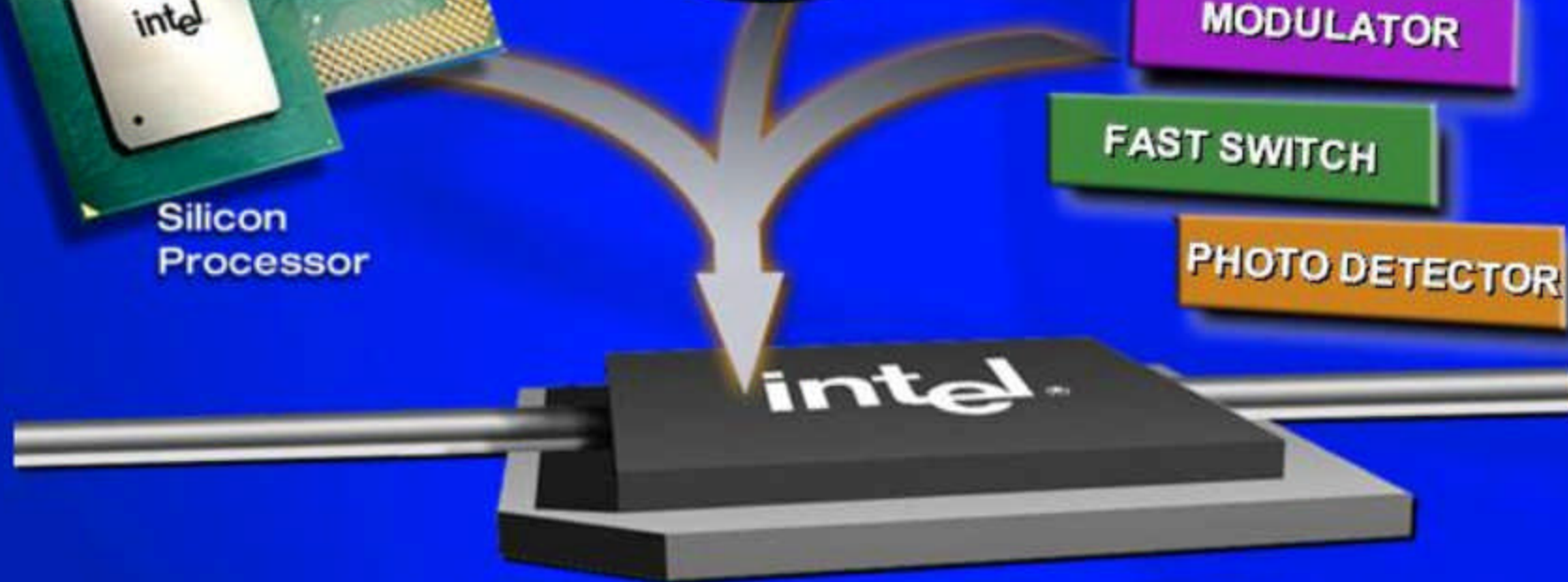
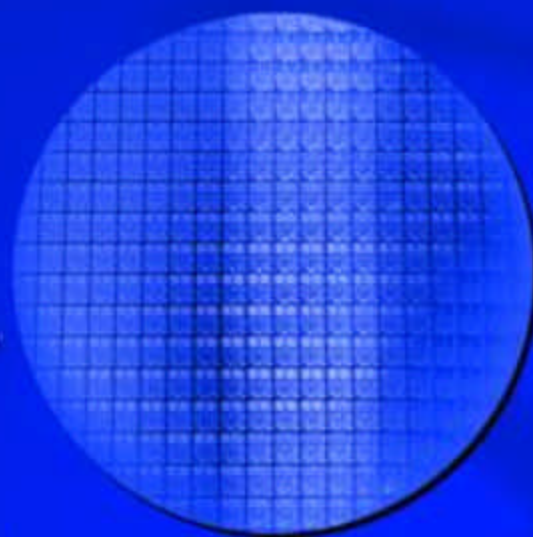
Moore's Law
– Intel Does it Best



RESEARCH

Silicon Photonics

Silicon-based Optical
Building Blocks

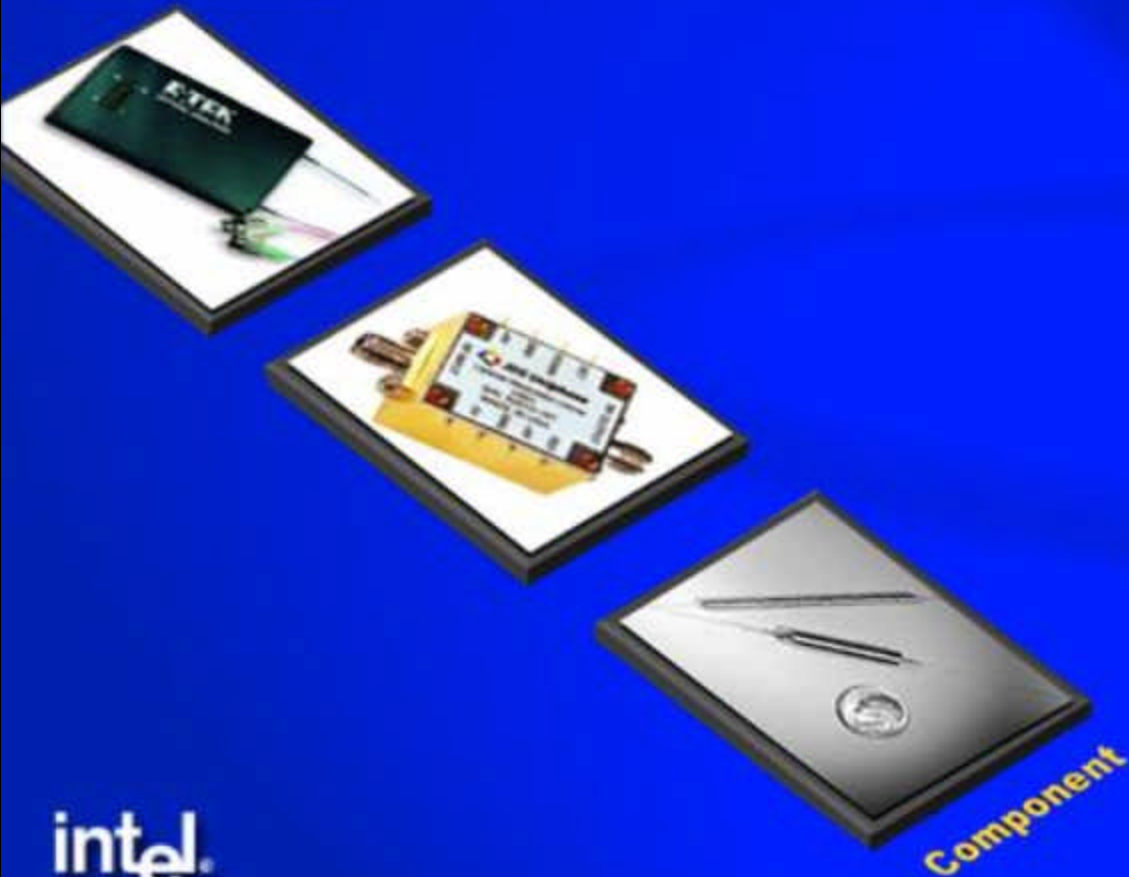


Integrated Electronics and Photonics



Next Steps: Integration Phases

**Discrete
Components**



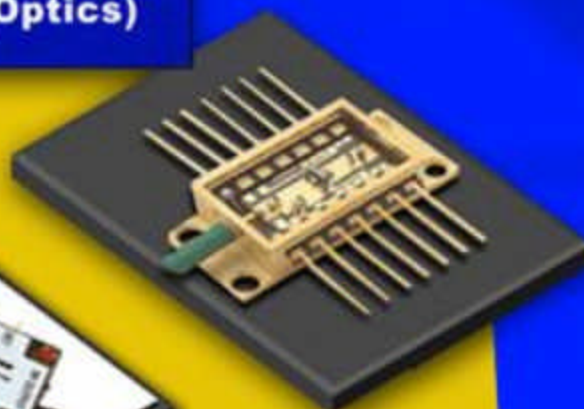
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Next Steps: Integration Phases

**Discrete
Components**

**Hybrid
Integration
(Optics)**



Module

Component

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Next Steps: Integration Phases

Discrete
Components

Hybrid
Integration
(Optics)

Hybrid
Integration
(Optics and
Electronics)

Transponder

Module

Component

intel.

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Fall 2002

Next Steps: Integration Phases

Discrete
Components

Hybrid
Integration
(Optics)

Hybrid
Integration
(Optics and
Electronics)

Optoelectronic
Integration
(Optics and Electronics)

Monolithic

Transponder

Module

Component

Sensor Networks



Sensor Networks

Sensing +

Computing +

Communicating



Communications-Computing

Great Duck Island Deployment



Great Duck Island

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Demo Fall 2002

Programming Sensor Networks Research

TinyOS

a component-based OS for the networked sensor regime

<http://webs.cs.berkeley.edu>

Berkeley
University of California

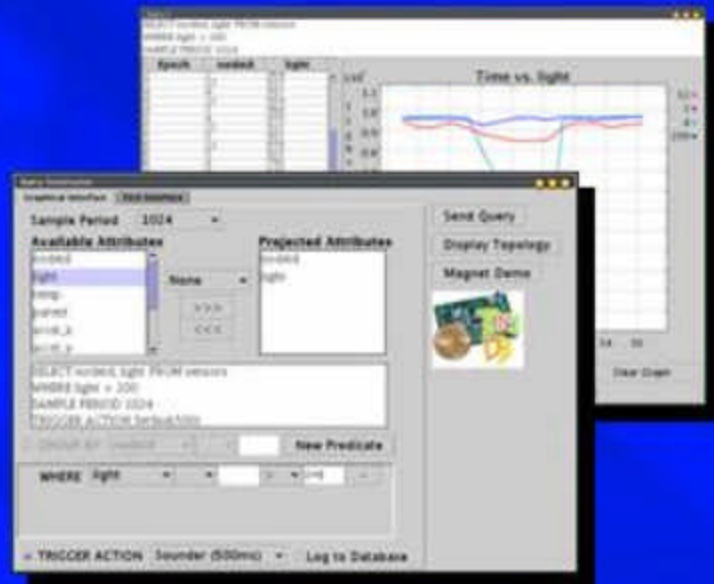
<http://berkeley.intel-research.net/tinydb/>

TinyDB: In-Network Query Processing in TinyOS

Samuel Madden, Joe Hellerstein, and Wei Hong

IR6-TR-02-014

August, 2002



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iMote Research



Configurable Silicon Radio



MOTE

(a small piece of silicon)

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Silicon Trajectory



What is Nanotechnology?

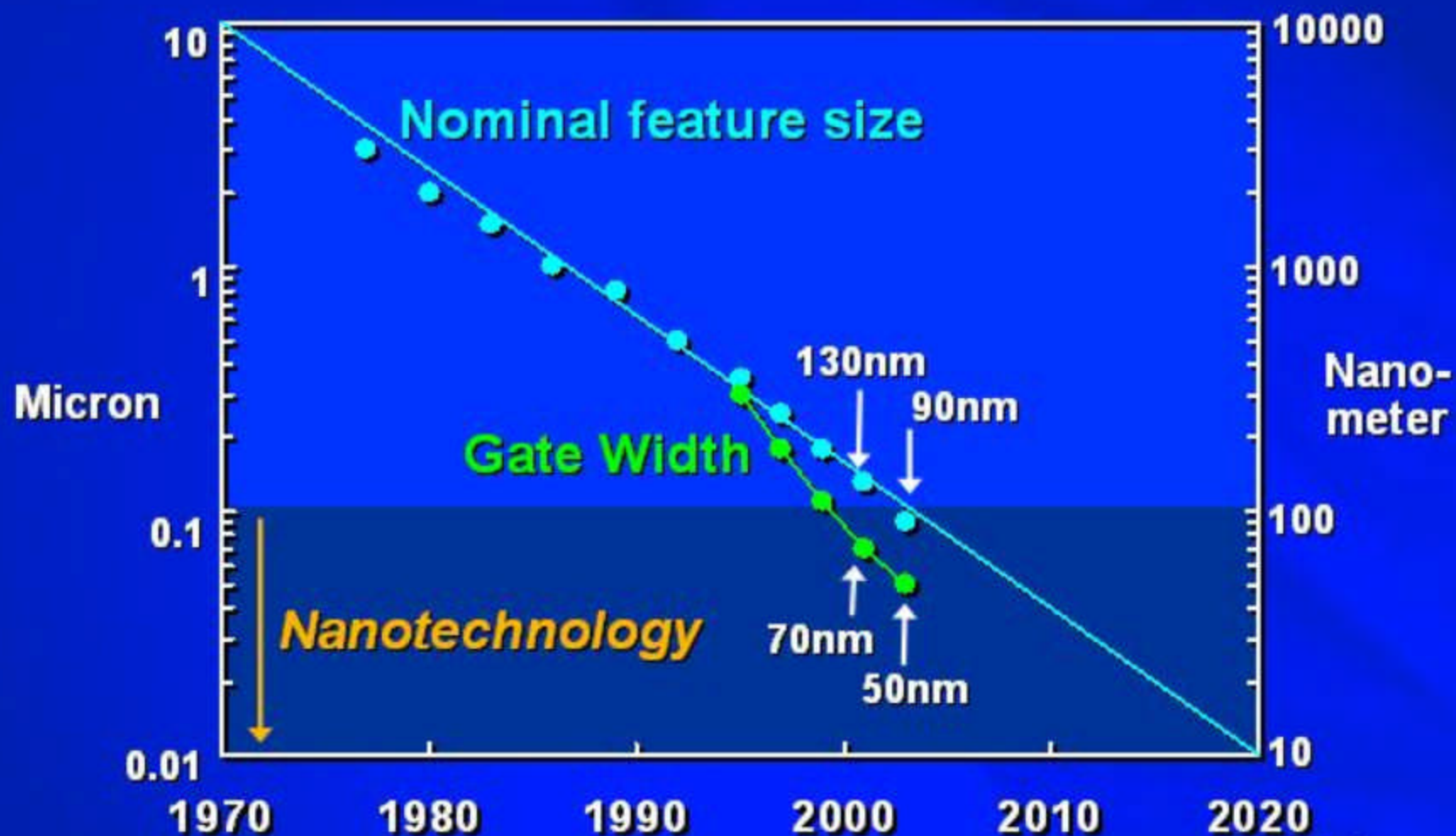
- a.** New structures like carbon nanotubes
- b.** Silicon devices made smaller
- c.** Arranging atoms and molecules
- d.** Letting atoms assemble themselves
- e.** Something far in the future
- f.** In production today
- g.** All of the above

Correct answer: g.

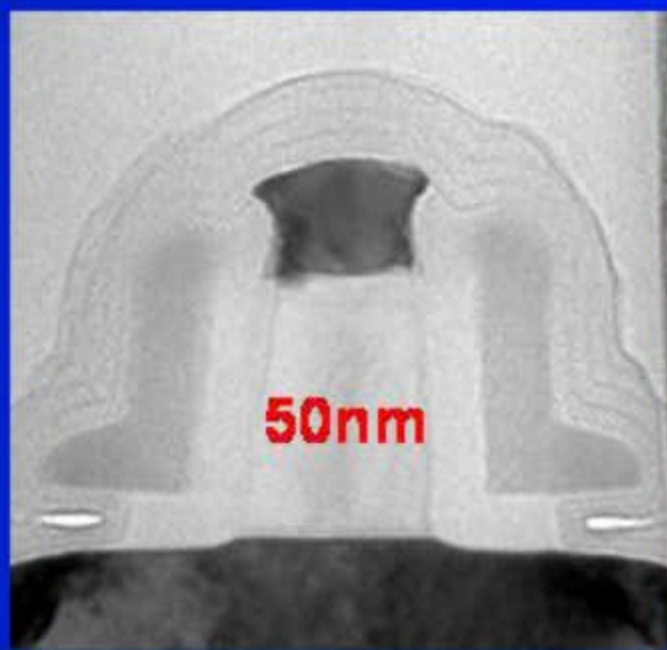
Nanotechnology features

- **Structures measured in nanometers**
 - Less than 0.1-micron (100nm)
- **New materials and device structures**
 - Incrementally changing silicon technology base
- **Materials manipulated on atomic scale**
 - In one or more dimensions
- **Increasing use of self-assembly**
 - Using chemical properties to form structures

Silicon Nanotechnology is Here!

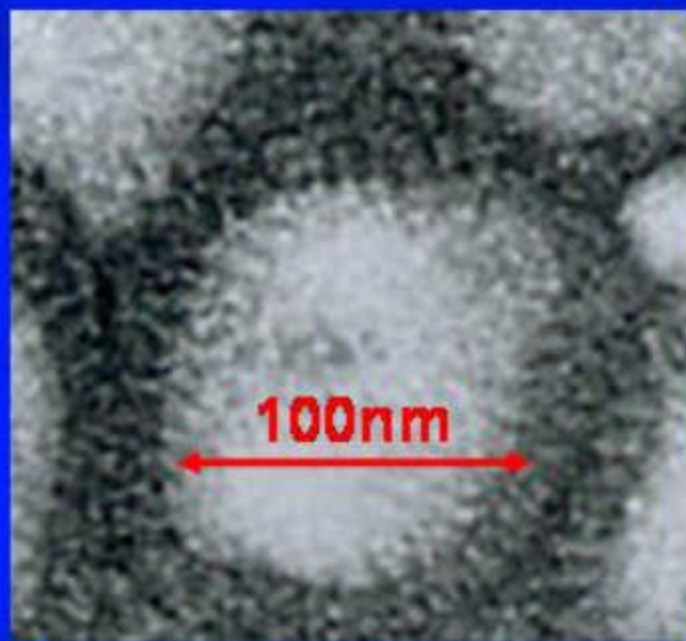


Silicon Devices Shrink to Virus Size



***Transistor for
90nm Process***

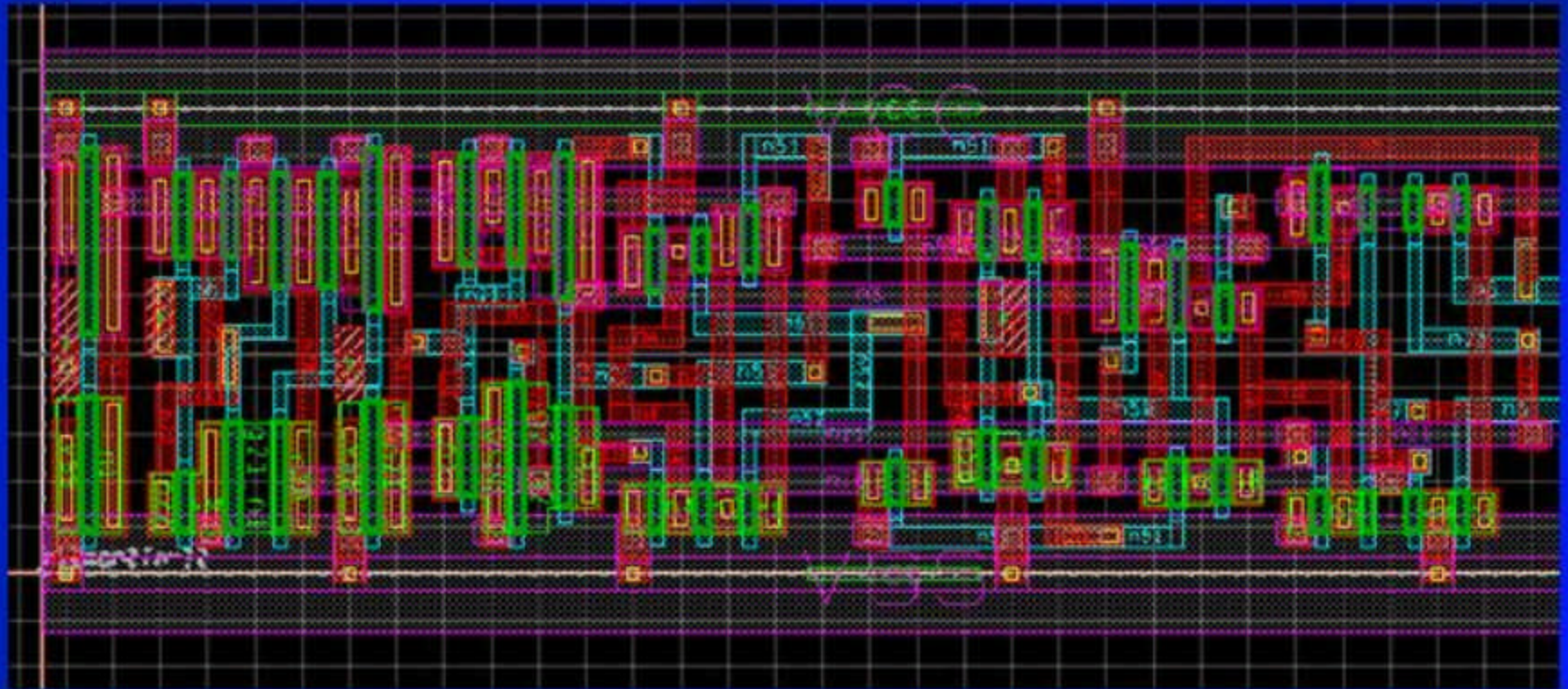
Source: Intel



Influenza virus

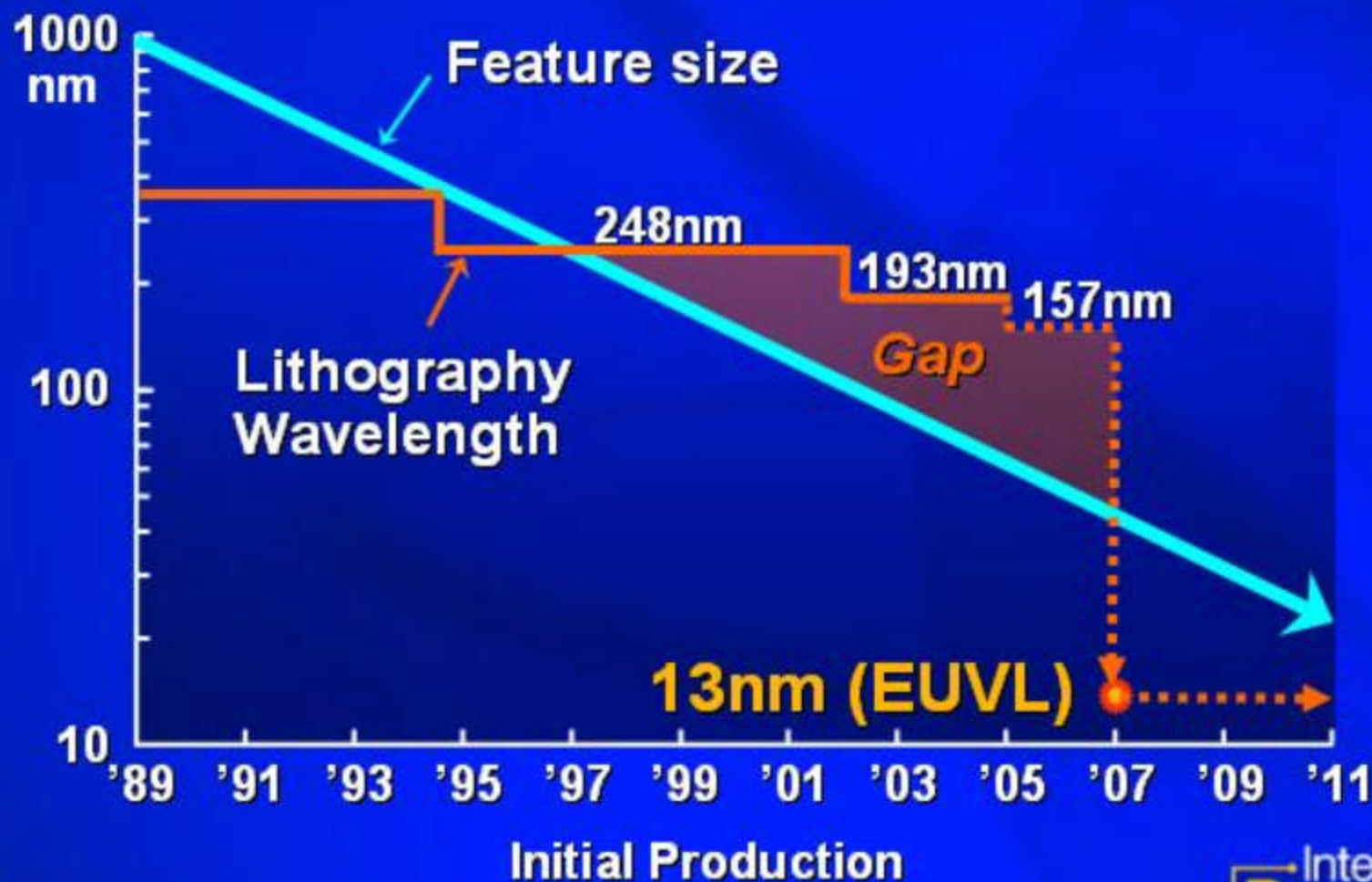
Source: CDC

Lithography is the Designer's "Brush"

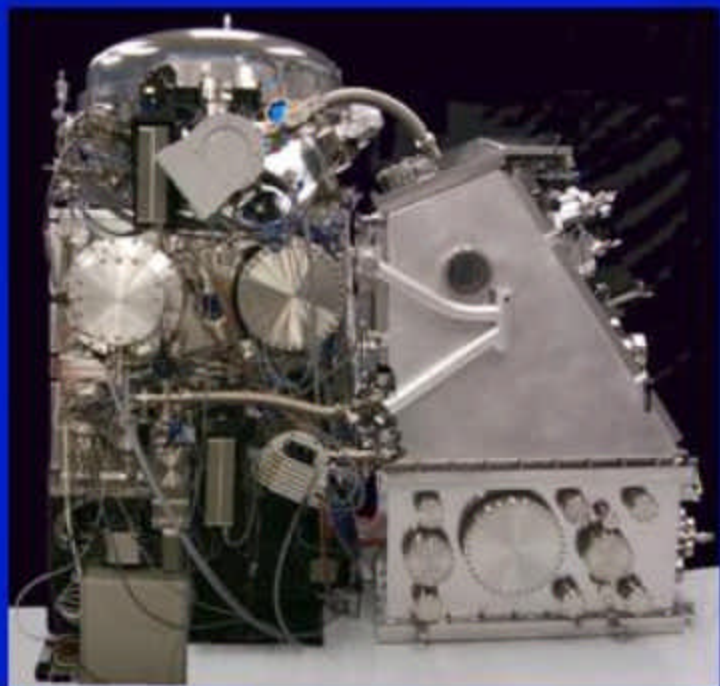


**Lithography is indispensable for
defining locations/configurations
of circuit elements/functions**

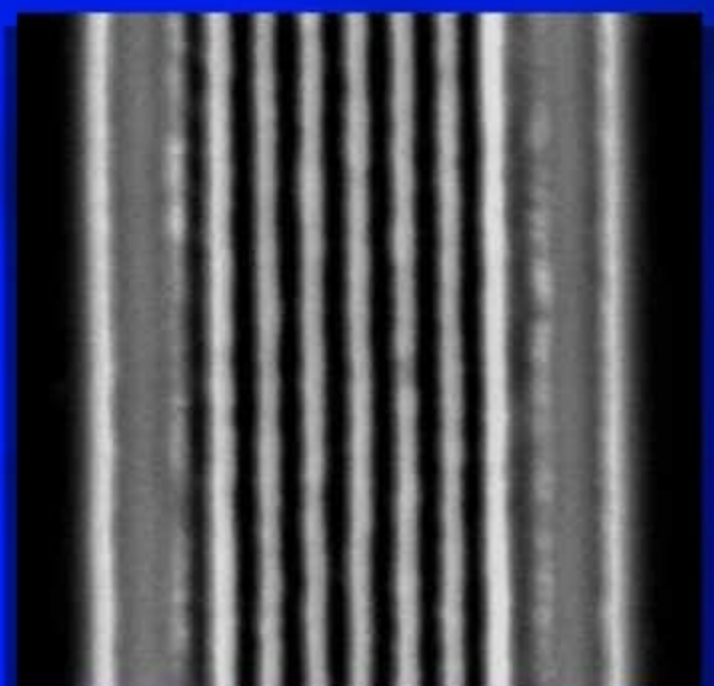
Lithography Gap to Close with EUVL



EUV LLC Consortium Demonstrates EUVL



***EUV Lithography
Prototype Exposure Tool***



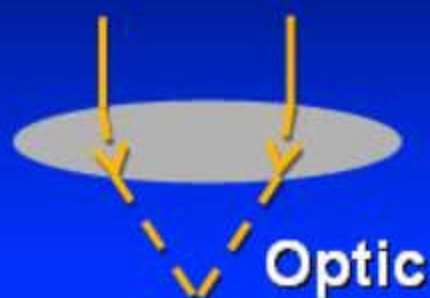
***50nm Lines Printed
with EUV Lithography***

Source: Sandia

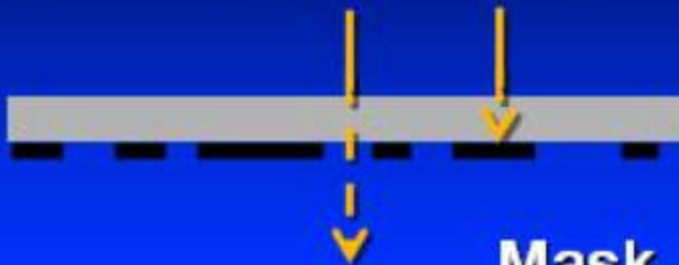
**EUV lithography is now
in commercialization phase**

EUVL Overcomes Optical Materials Limits

Conventional lithography (refractive)



Optic



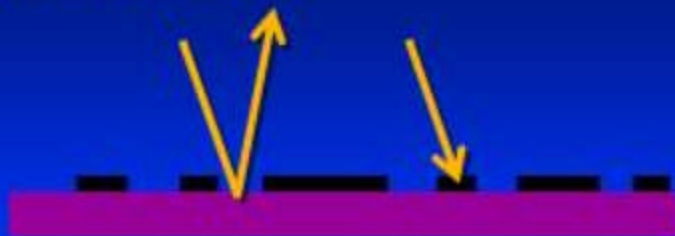
Mask

Optical materials do not transmit short wavelengths

EUV lithography (reflective)



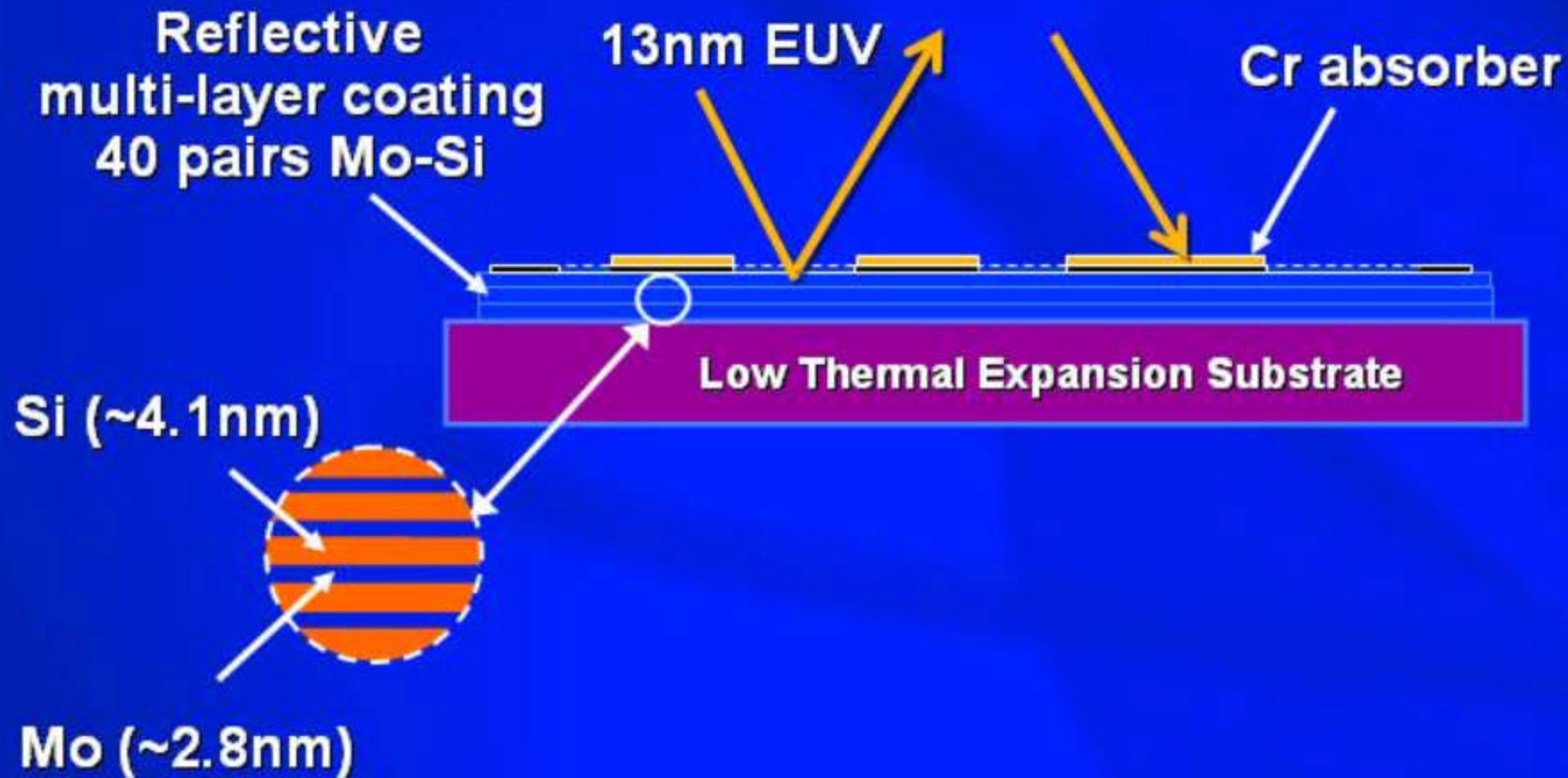
Optic



Mask

Multi-layer coating reflects short wavelengths

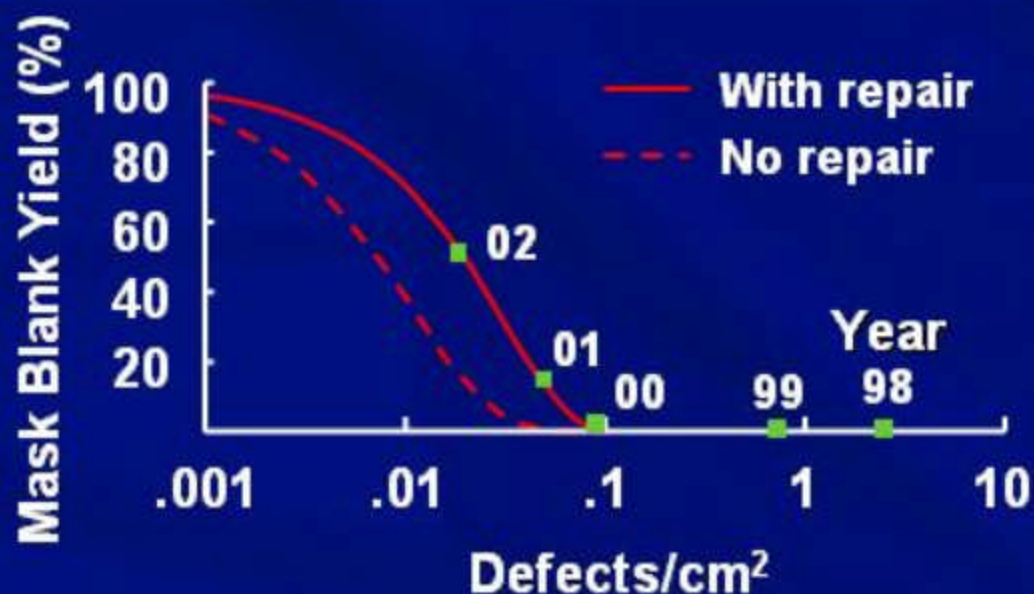
EUV Reflective Mask Structure



EUV Mask Yield Breakthroughs



EUV Mask

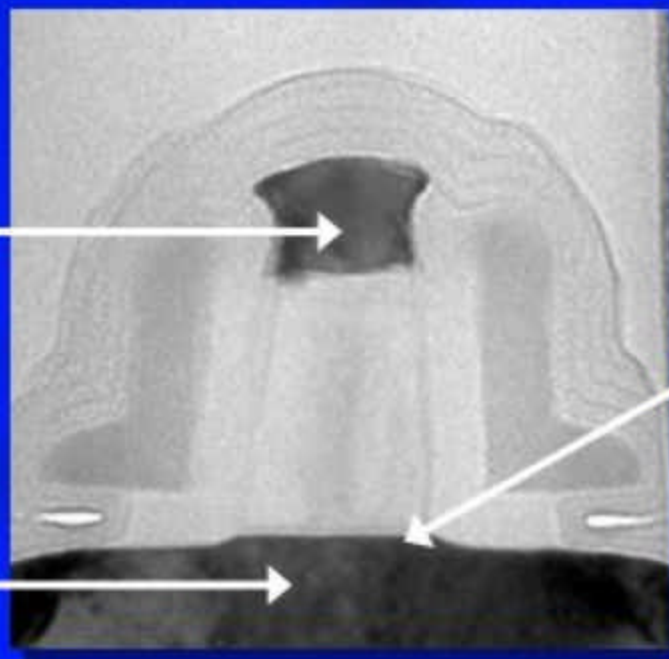


New Materials, Devices Extend Si Scaling

Changes Made

Gate
Silicide
added

Channel
Strained
silicon



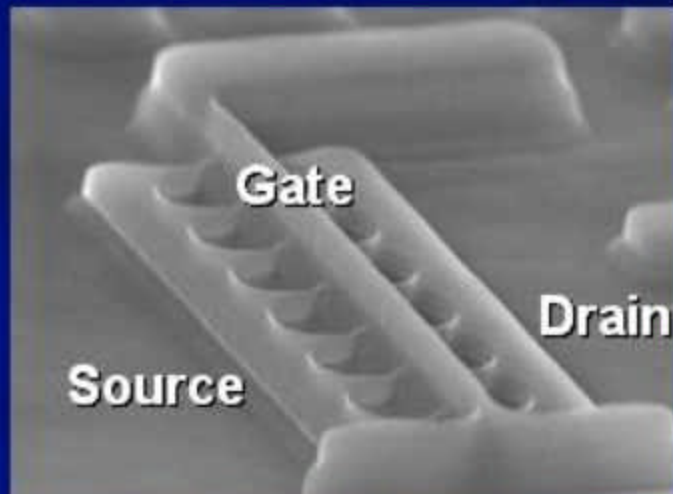
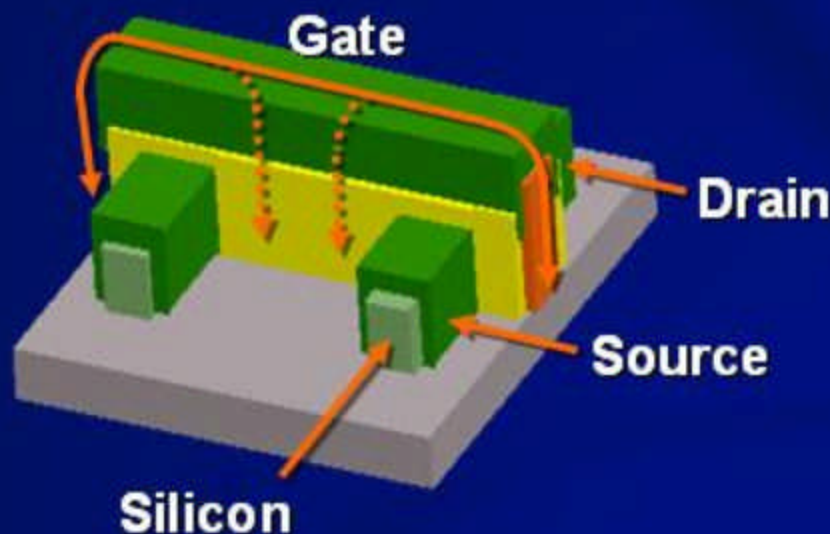
Transistor

Future Options

High-k
gate
dielectric

New
transistor
structure

Experimental Tri-Gate Transistor



Source: Intel

- Improved version of TeraHertz transistor
 - Better performance
 - Scalable to smaller sizes
- Technical details to be presented
 - ISSDM Conference, Japan, Sept 17, 2002

New Materials, Devices Extend Si Scaling

Changes Made

Metal lines

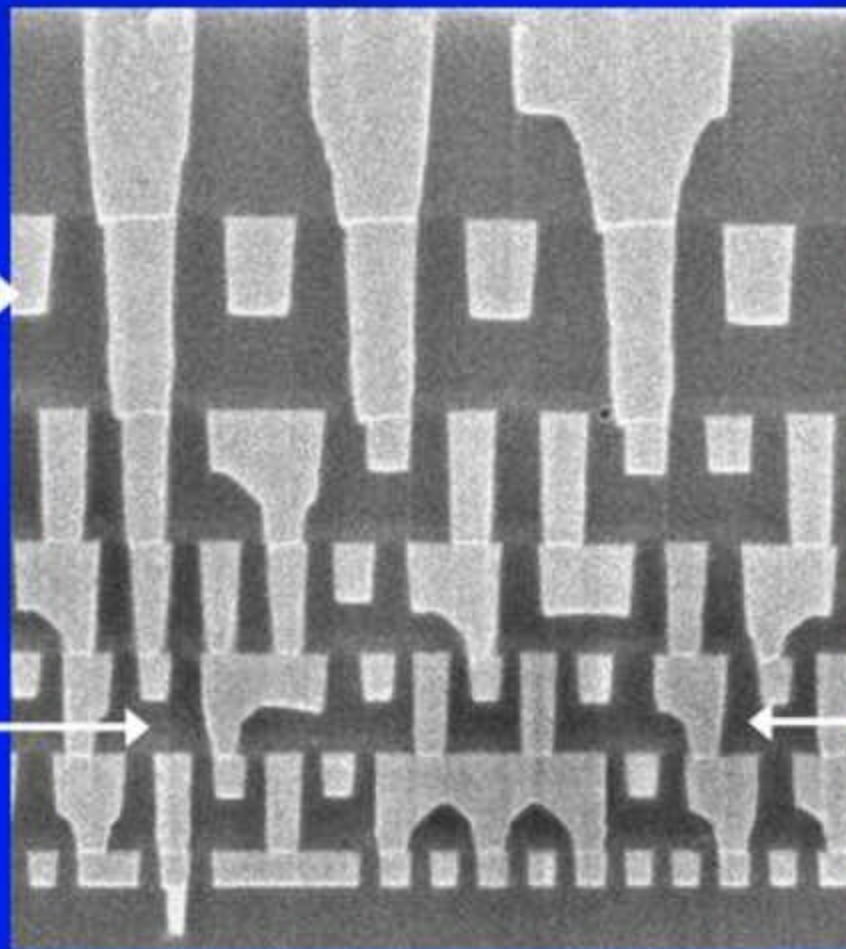
Al → Cu

Insulating dielectric

$\text{SiO}_2 \rightarrow \text{SiOF}$

→ CDO

(low-k)



Future Options

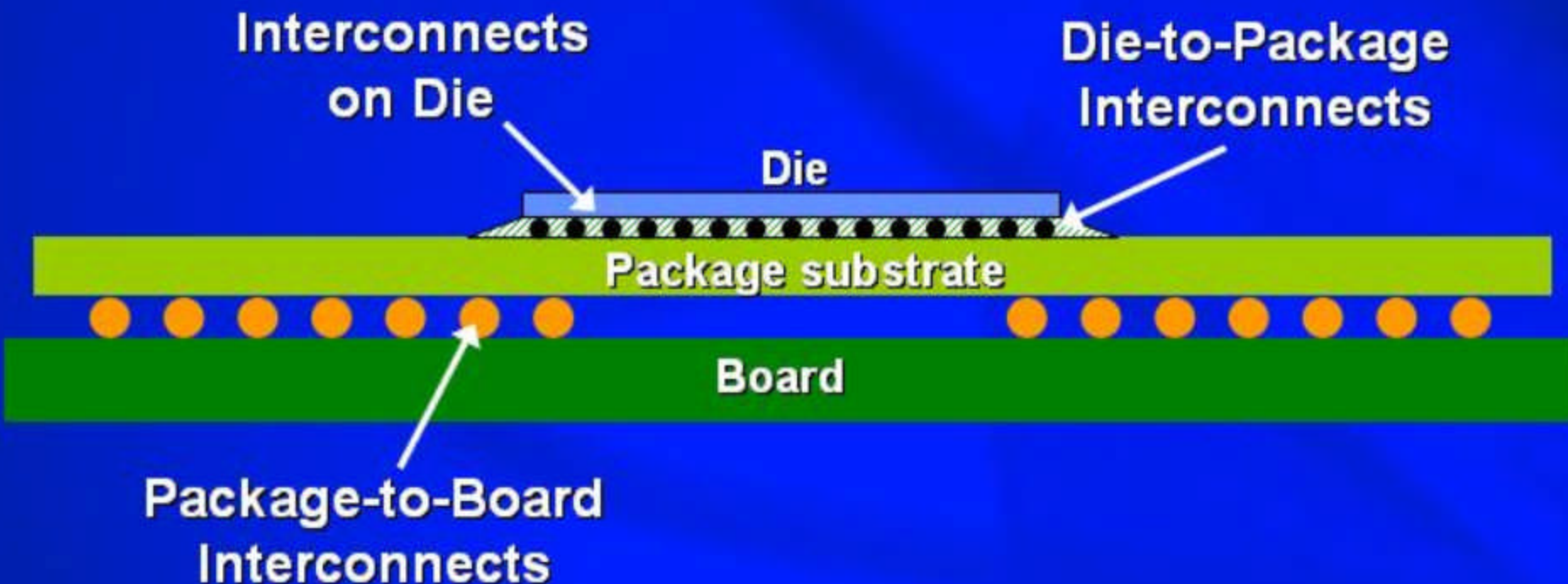
Ultra Low-k Dielectric

Interconnects

Source: Intel

Die/Package Integration More Critical

Points of Vulnerability:

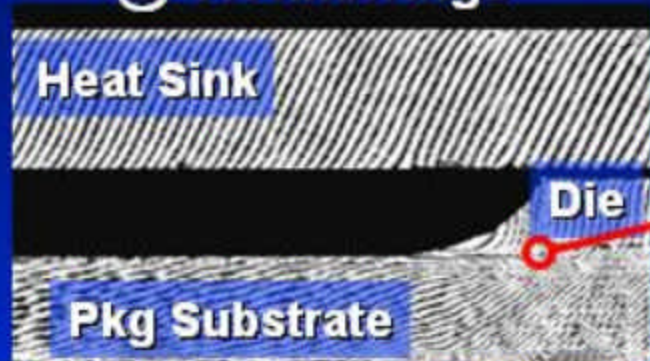


Materials and structures must withstand thermal-mechanical stresses

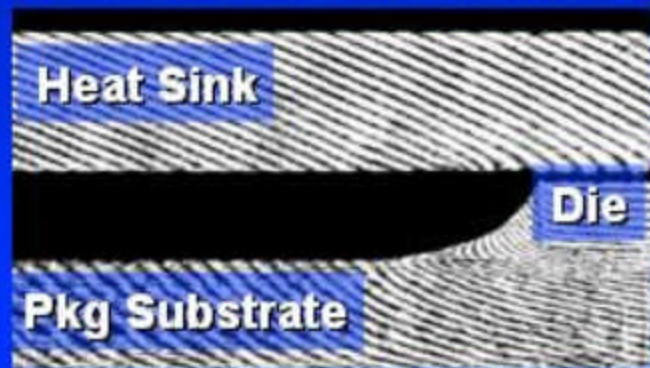
Analytical Tools For Nanotechnology

Package/Interconnect Deformation Measurements

**Conventional Moiré
@ 417nm/fringe**



V-field (Vertical Displacements)



U-field (Horizontal Displacements)

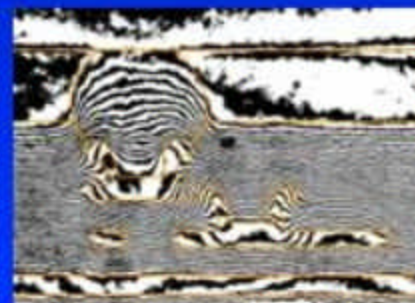
**Micro-Moiré
@ 52 nm/fringe**



190 μm

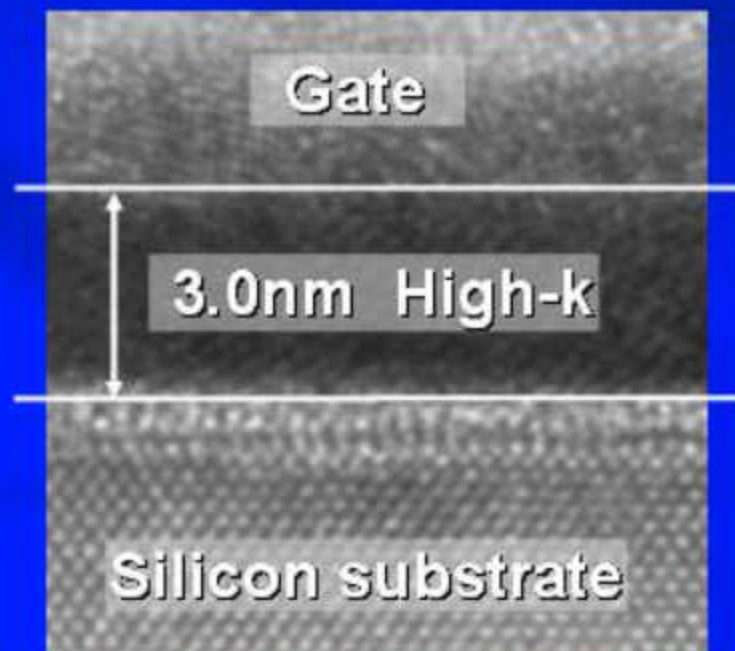
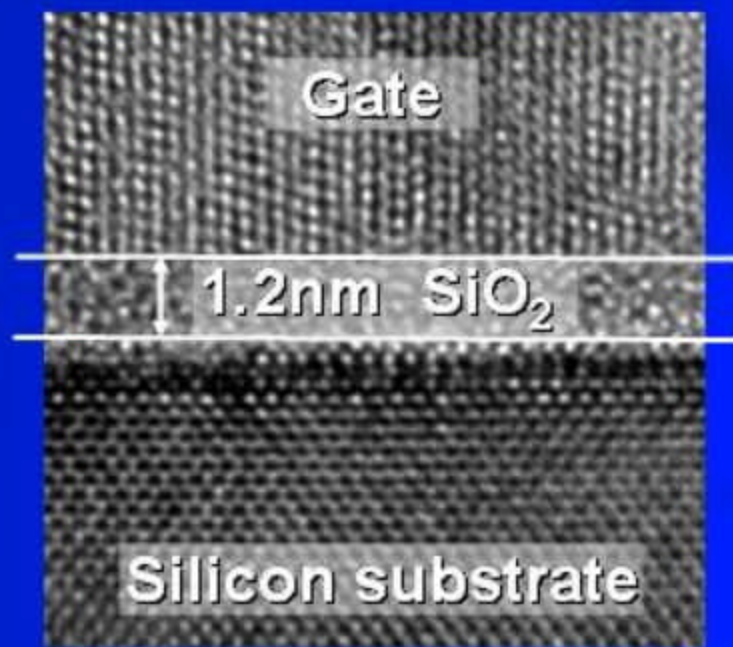


U-field (Horizontal)



V-field (Vertical)

Nanotechnology for Gate Dielectrics

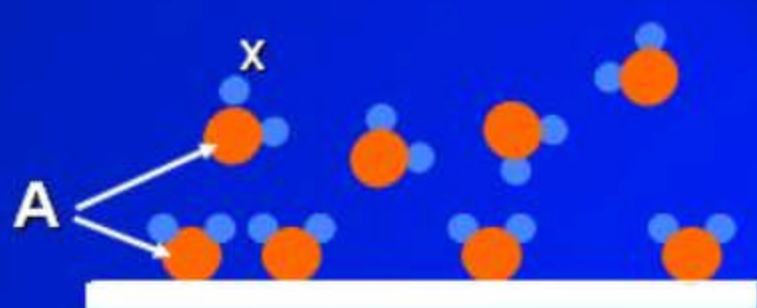


Source: Intel

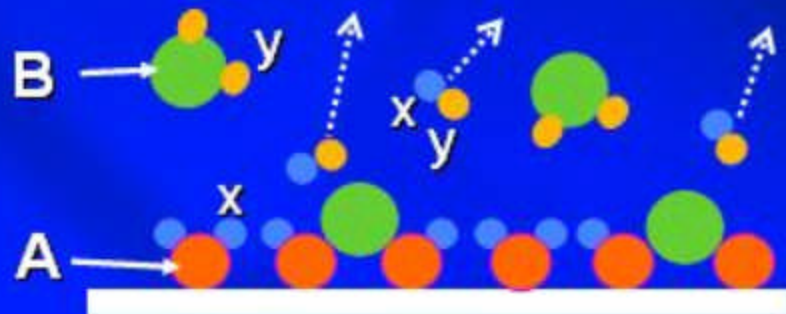
	<u>90nm process</u>	<u>Experimental high-k</u>
Capacitance	1X	1.6X
Leakage	1X	< 0.01X

Integration is the key challenge

Crafting Films with Atomic Layer Deposition



Step 1



Step 3



Step 2



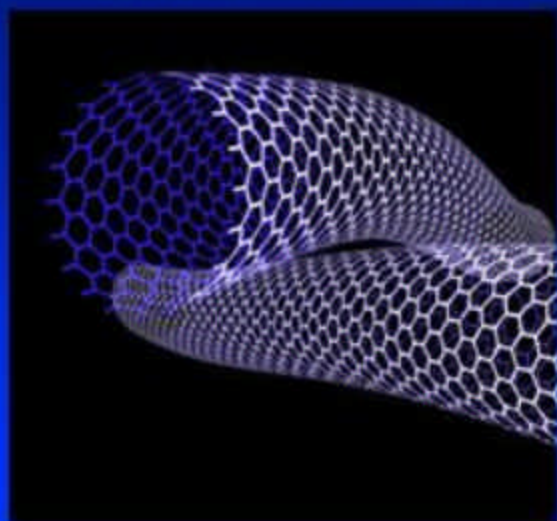
Step 4

ALD: Today's nanotechnology for self-assembly by atomic layer

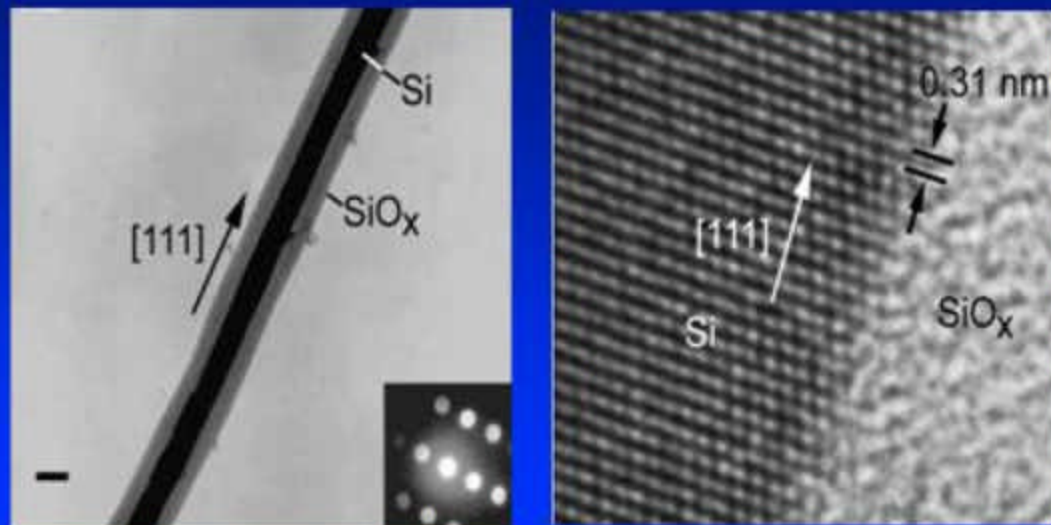
Nanotechnology Futures (> 2010 ?)

- Many options including nanotubes/nanowires
- Collaborations with universities in progress

Carbon Nanotube



Silicon Nanowire



Source: Morales & Lieber, Science **279**, 208 (1998)

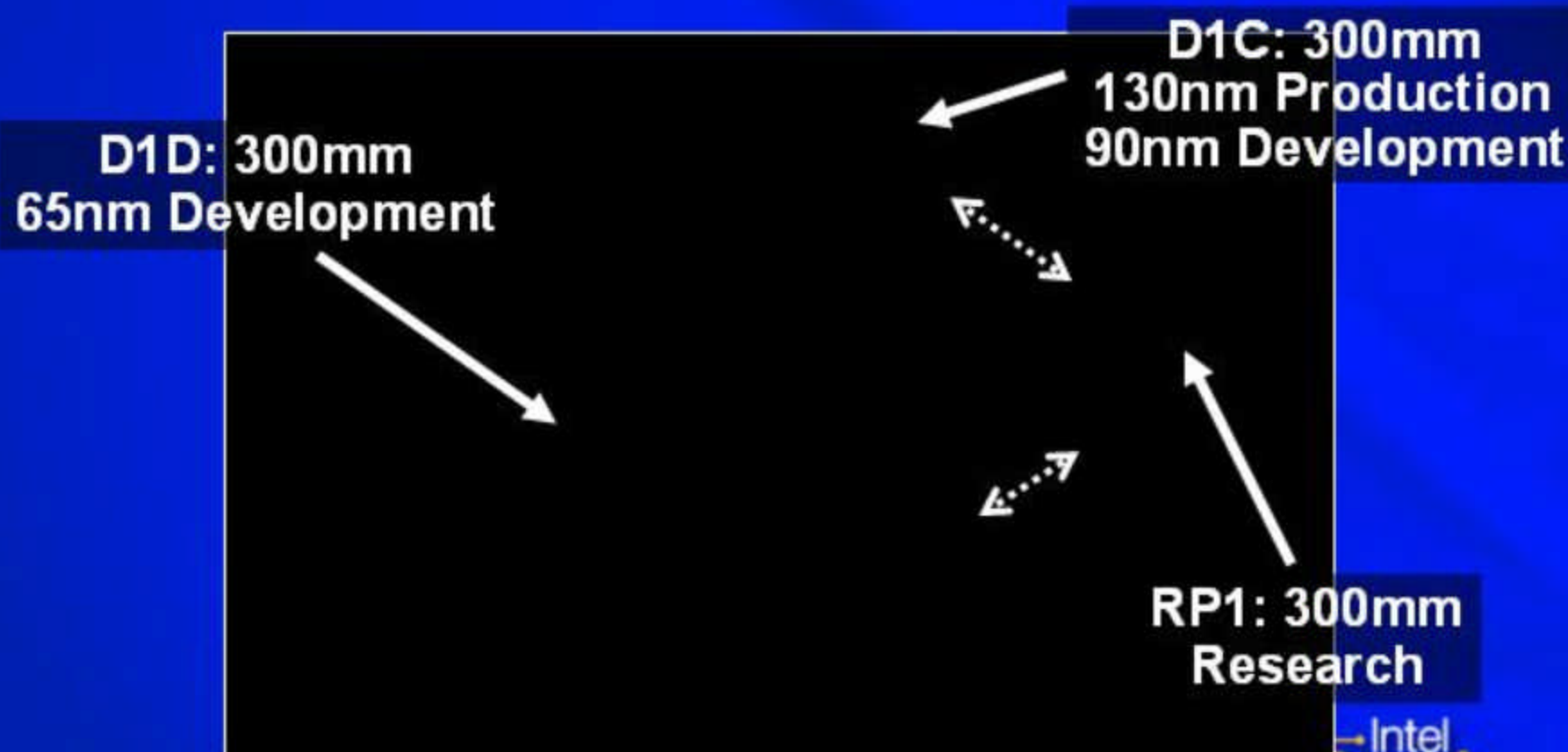
Intel Involved in University Research

Intel-supported Nanotechnology Research at Universities



Speeding Nanotechnology to Production

Linking 300mm Research, Development, Production



Nanotechnology for Computing and Communications

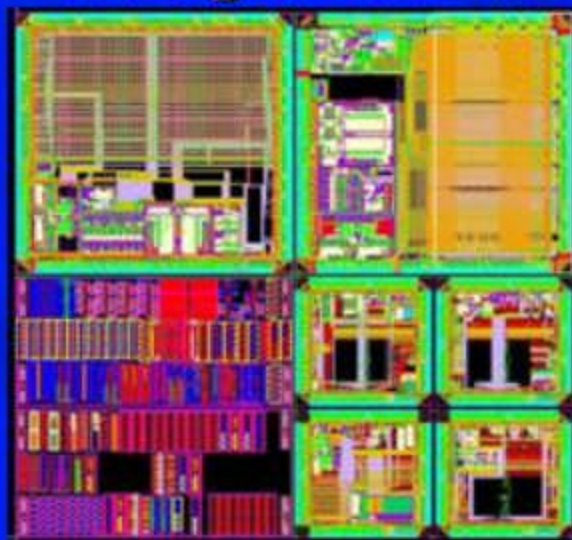
Process Development Test Vehicles

52Mb SRAM



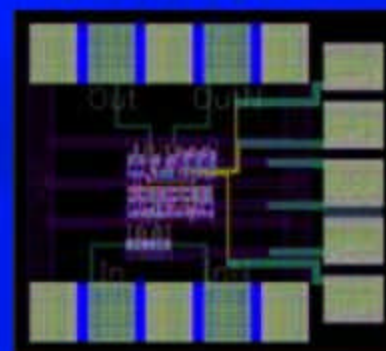
For
Processors

WCDMA
Analog/RF circuits



For Wireless
(Cellular)

40 Gb/s SiGe
test circuit



For Optical
Communications

Intelligent Silicon

Nano is Here

New Devices,
Materials, and Processes

EXTENDING MOORE'S LAW

Discrete

SSI

LSI

VLSI

Biological
Nano

Fluidics

Wireless

Mechanical

EXPANDING



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Intelligent Silicon

Nano is Here

New Devices,
Materials, and Processes

Expanding the Silicon Canvas

EXTENDING MOORE'S LAW

Discrete

SSI

LSI

VLSI

Biological
Nano

Fluidics

Wireless

EXPANDING

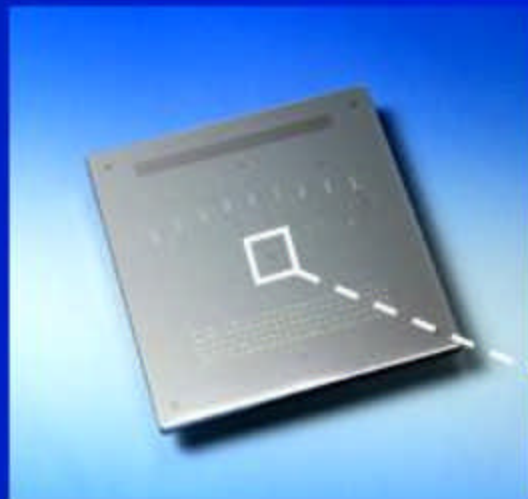


Silicon Innovation Enabling Convergence

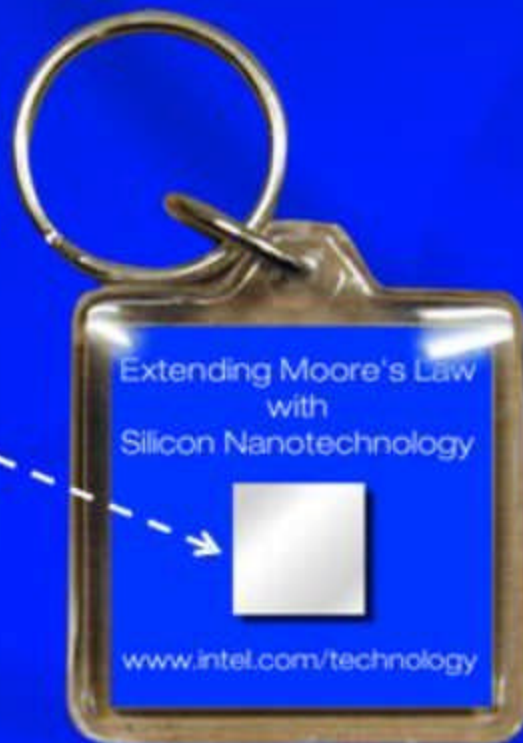
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A Piece of Nanotechnology



EUV mask



**80-layer EUV reflective coating
on thin substrate**

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